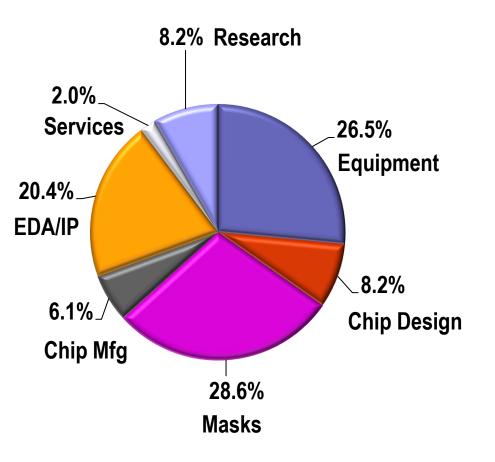
August 2013 eBeam Initiative Survey

Goals:

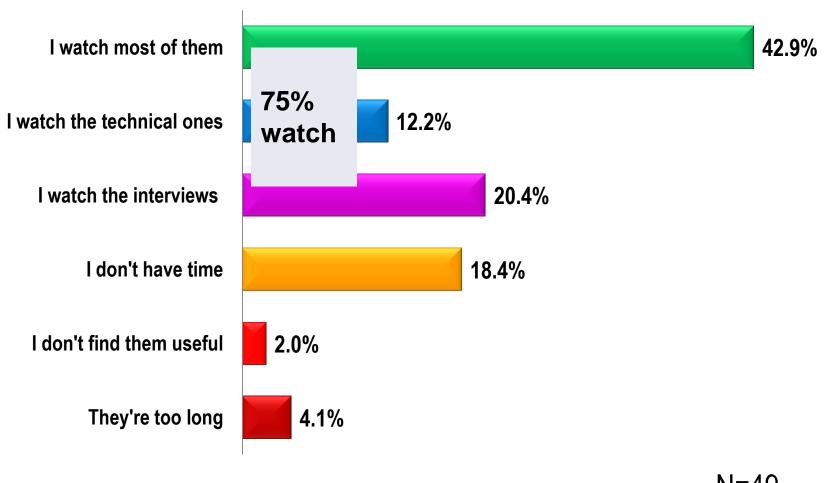
- Increase the voice of the eBeam community
- Two-way communication with members
- Thank you for your participation with 49 responses (n=49)







Thank you for watching the Fine Line

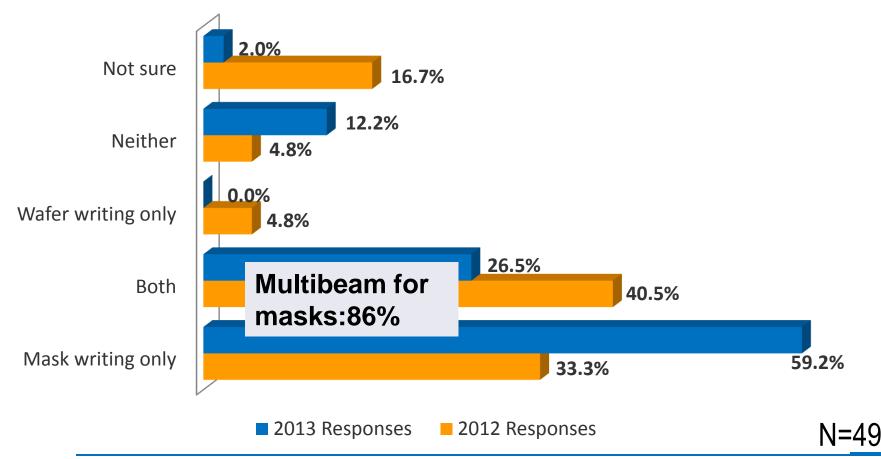


N=49

Multibeam for Mask Sentiment Increased



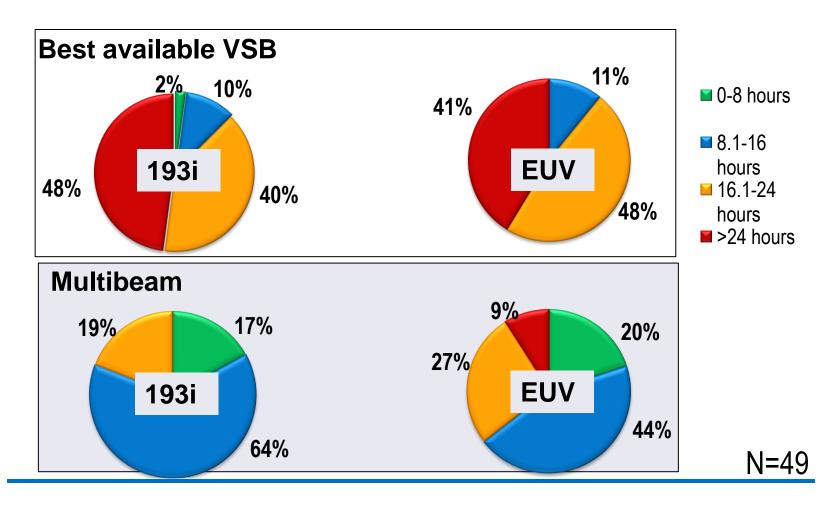
Q: Do you believe that multibeam technology will be used for mask or wafer writing production by 2016?





Multibeam Expected to Solve Write Times

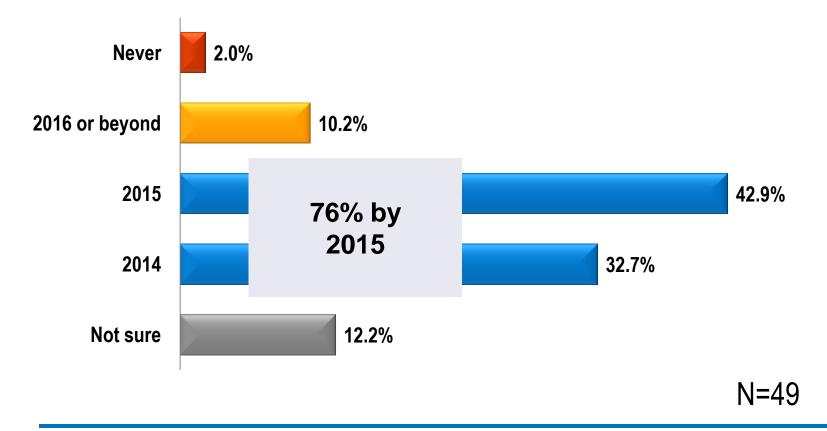
Q: At 10nm, what is your prediction for mask write times?





Majority Predict Mask CDU Impact by 2015

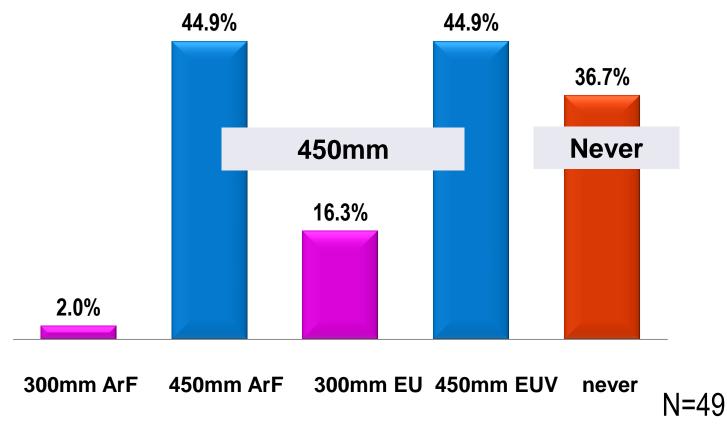
Q: When will changes need to be made to MDP in order to account for shape-dependent mask CDU?



Different Views on Mask Sizes



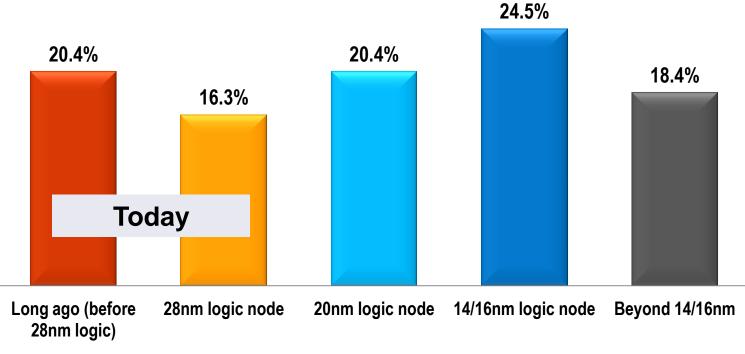
Q: With which evolution of wafers do you think 8-inch or greater mask sizes will become a production need?



Mask Accuracy is an Issue Today



Q: When did you start – or do you anticipate – seeing mask hotspots as a significant issue?

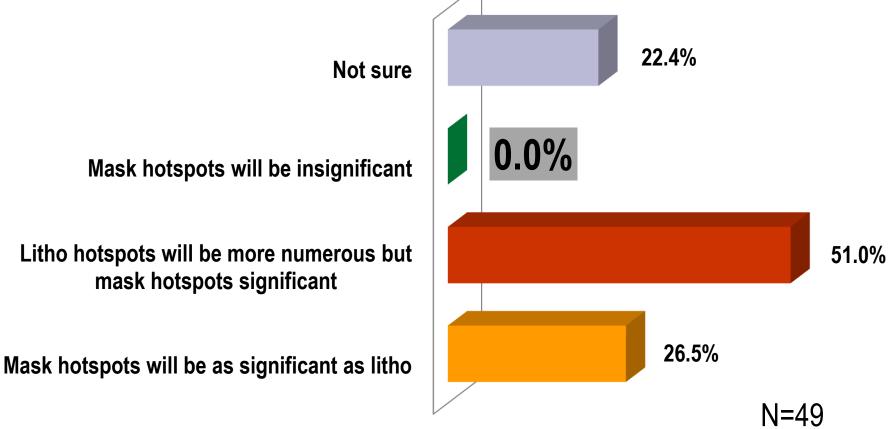


N=49

2020: Mask Hotspots Significant



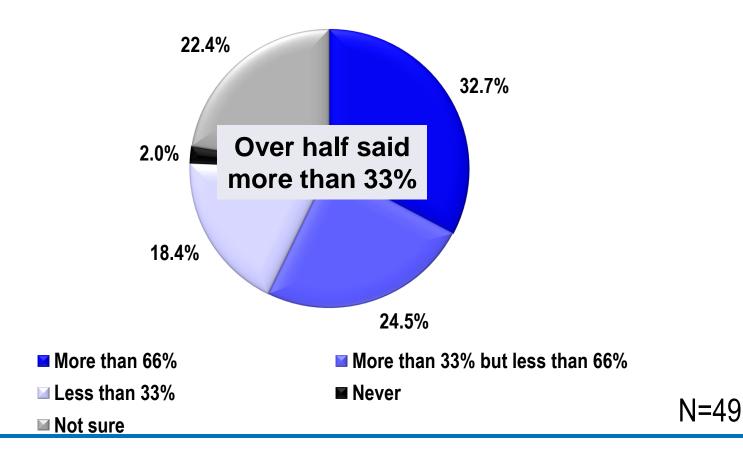
Q: By 2020, what significance do you expect mask hotspots to have for critical layers processed by immersion lithography with multiple patterning?





2020: GPGPU Usage is Expected

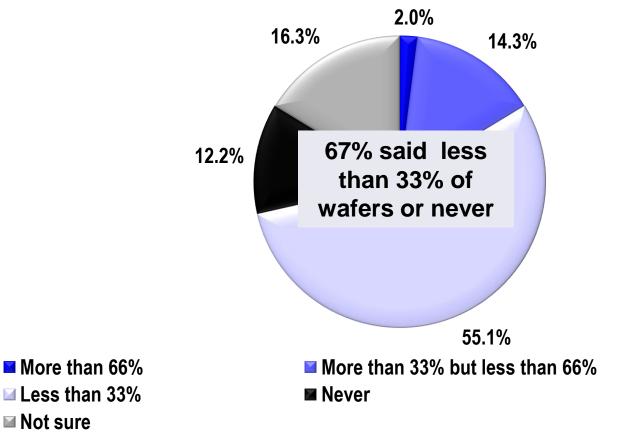
Q: By 2020, what percentage of simulation-intensive applications in EDA will use GPUs?





2020: Early Days for DSA Predictions

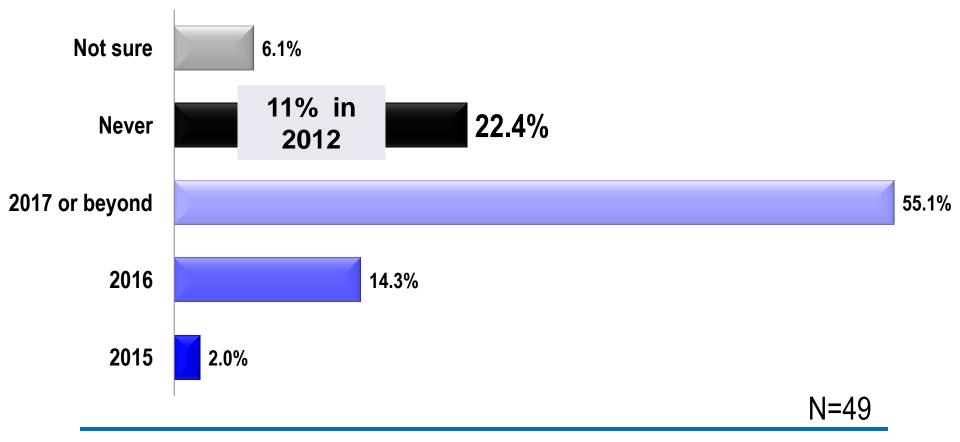
Q: By 2020, what percentage of wafers will be manufactured using at least one layer processed with DSA?



EUV Expectations Still Set in the Future More than twice as many said "Never" vs 2012



Q: In what year do you predict EUV will be used in volume production for SoCs?





Thank you to those who participated in the survey!

Feedback and questions for future surveys welcome – send to jan@williscalibra.com